

2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- General purpose

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.090g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	2	Α	
V_{RRM}	200 - 1000	V	
I _{FSM}	50	Α	
T_{JMAX}	150	°C	
Package	DO-214AA (SMB)		
Configuration	Single die		











ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2D-T	RS2G-T	RS2J-T	RS2K-T	RS2M-T	UNIT
Marking code on the device			RS2D	RS2G	RS2J	RS2K	RS2M	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		I _F	2					Α
Surge peak forward current t = 8.3ms			50					Α
single half sine-wave superimposed on rated load	t = 1.0ms	I _{FSM}	128					Α
Junction temperature		T _J	-55 to +150					°C
Storage temperature		T _{STG}	-55 to +150					°C



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R _{OJL}	20	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	78	°C/W	
Junction-to-case thermal resistance	R _{OJC}	26	°C/W	

Thermal Performance Note: Units mounted on PCB (10mm x 10mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (TA = PARAMETER		CONDITIONS SYMBO		TYP	MAX	UNIT
I ARAWE I ER			O I M DOL	1.01	WAX	V
		$I_F = 1A, T_J = 25^{\circ}C$	V _F		1.00	·
	RS2D-T	$I_F = 2A, T_J = 25^{\circ}C$		1.11	1.30	V
	RS2G-T	$I_F = 1A, T_J = 125^{\circ}C$		0.88	-	V
		$I_F = 2A, T_J = 125^{\circ}C$		0.96	1.18	V
		$I_F = 1A, T_J = 25^{\circ}C$		1.03	-	V
Forward voltage ⁽¹⁾	RS2J-T	$I_F = 2A, T_J = 25^{\circ}C$	\/	1.13	1.30	V
Forward voltage	K32J-1	I _F = 1A, T _J = 125°C	V _F	0.85	-	V
		I _F = 2A, T _J = 125°C		0.95	1.17	V
		I _F = 1A, T _J = 25°C	V _F	0.95	-	V
	RS2K-T	I _F = 2A, T _J = 25°C		1.03	1.30	V
	RS2M-T	I _F = 1A, T _J = 125°C		0.82	-	V
		I _F = 2A, T _J = 125°C		0.90	1.09	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C	I _R	-	5	μA
		T _J = 125°C		-	150	μA
	RS2D-T RS2G-T	$I_F = 0.5A, I_R = 1.0A$ $I_{rr} = 0.25A$	t _{rr}	-	150	ns
Reverse recovery time	RS2J-T			-	250	ns
	RS2K-T RS2M-T	3.257		-	500	ns
Junction capacitance		1MHz, V _R = 4.0V	CJ	50	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
RS2x-T	DO-214AA (SMB)	3,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 200V(RS2D-T) to 1000V(RS2M-T)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

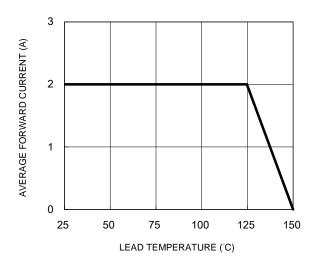


Fig.3 Typical Reverse Characteristics

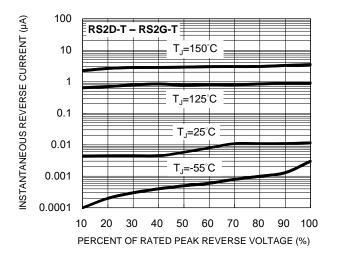


Fig.5 Typical Reverse Characteristics

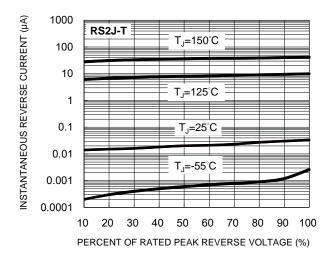


Fig.2 Typical Junction Capacitance

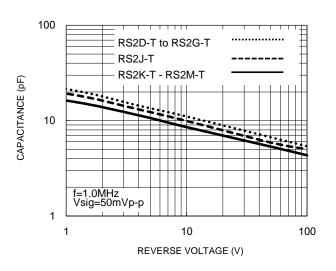


Fig.4 Typical Forward Characteristics

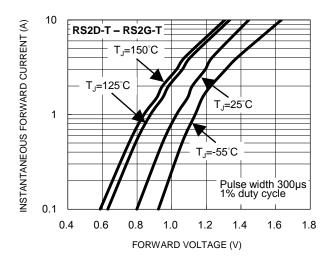
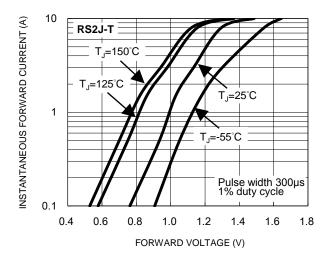


Fig.6 Typical Forward Characteristics





CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.7 Typical Reverse Characteristics

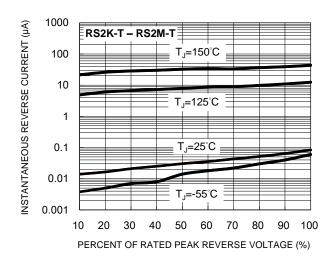


Fig.8 Typical Forward Characteristics

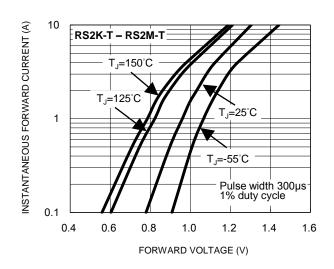
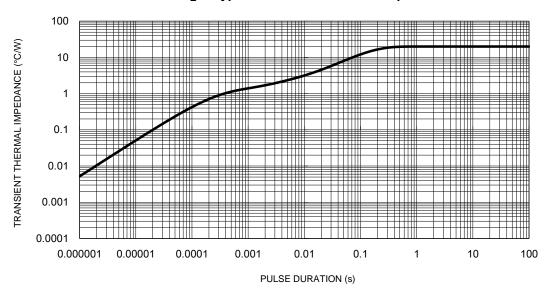


Fig.9 Typical Transient Thermal Impedance

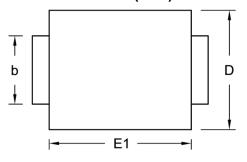


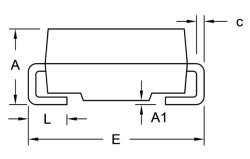




PACKAGE OUTLINE DIMENSIONS

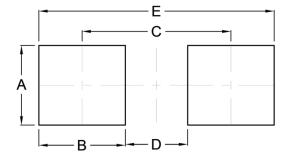
DO-214AA (SMB)





DIM.	Unit (mm)		Unit (inch)	
DIW.	Min.	Max.	Min.	Max.
Α	1.95	2.65	0.077	0.104
A1	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
С	0.15	0.31	0.006	0.012
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.60	0.030	0.063

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.30	0.091
В	2.50	0.098
С	4.30	0.169
D	1.80	0.071
E	6.80	0.268

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code

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